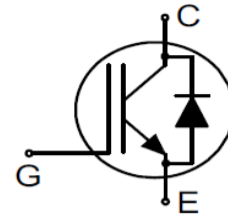


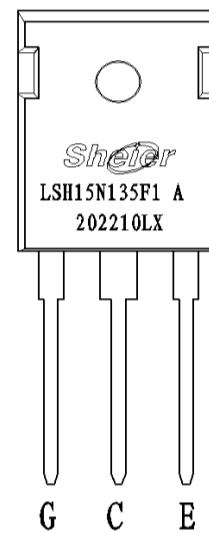
## Features

- Offers high breakdown voltage to 1350V for improved reliability
- Powerful monolithic body diode with low forward voltage designed for soft commutation only
- very tight parameter distribution
- high ruggedness, temperature stable behavior
- low VCEsat
- easy parallel switching capability due to positive temperature coefficient in VCEsat
- Qualified according to JESD-022 for target applications



## Applications

- Inductive cooking
- Inverterized microwave ovens
- Resonant converters
- Soft switching applications



## Package pin definition

- Pin 1 -- Gate
- Pin 2 & Backside -- Collector
- Pin 3 -- Emmitter



## Package Marking and Ordering Information

Part #	V <sub>ce</sub>	I <sub>c</sub>	V <sub>cesat</sub> , T <sub>vj</sub> =25°C	T <sub>vjmax</sub>	Package
LSH15N135F1 A	1350V	15A	1.75V	175	TO-247-3L

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-Emmitter voltage	$V_{CE}$	1350	V
CD collector current $T_C = 25\text{ }^\circ\text{C}$ $T_C = 100\text{ }^\circ\text{C}$	$I_C$	30.0 15.0	A
Pulsed collector current ( $T_C = 25\text{ }^\circ\text{C}$ , $t_p$ limited by $T_{jmax}$ )	$I_{C\ pulse}$	45.0	A
Non repetitive peak collector current <sup>1)</sup>	$I_{CSM}$	200.0	A
Turn off safe operating area $V_{CE} \leq 1350\text{V}$ , $T_{vj} \leq 175\text{ }^\circ\text{C}$	-	45.0	A
Diode forward current $T_C = 25\text{ }^\circ\text{C}$ $T_C = 100\text{ }^\circ\text{C}$	$I_F$	30.0 15.0	A
Diode pulsed current ( $T_C = 25\text{ }^\circ\text{C}$ , $t_p$ limited by $T_{jmax}$ )	$I_{F\ pulse}$	60.0	A
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Power dissipation $T_c = 25\text{ }^\circ\text{C}$	$P_{tot}$	350	W
Power dissipation $T_c = 100\text{ }^\circ\text{C}$		179	
Operating junction and storage temperature	$T_j, T_{stg}$	-40...+175	$^\circ\text{C}$
Soldering temperature, (0.063in.) form case for 10s	wave soldering 1.6mm	260	$^\circ\text{C}$
Mounting torque,M3 Screw porcesses:3	Maximum of mounting	0.6	Nm

**Thermal Resistance**

Parameter	Symbol	Value	Unit
IGBT thermal resistance, junction case. Max	$R_{thJC}$	0.42	$^\circ\text{C/W}$
Diode thermal resistance, junction case. Max	$R_{thJC}$	0.42	
Thermal resistance, junction – ambient. Max	$R_{thJA}$	40	

<sup>1)</sup> capacitor charging saturation current limited by  $T_{vjmax} < 175\text{ }^\circ\text{C}$  and  $t_p < 3\text{ }\mu\text{s}$

**Electrical Characteristic (at T<sub>j</sub> = 25 °C, unless otherwise specified)**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	V <sub>(BR)CES</sub>	V <sub>GE</sub> = 0V, I <sub>C</sub> = 0.5mA	1350	-	-	V
Collector-emitter saturation voltage	V <sub>CEsat</sub>	V <sub>GE</sub> = 15.0V, I <sub>C</sub> = 15A				V
		T <sub>vj</sub> = 25 °C	-	1.75	1.85	
		T <sub>vj</sub> = 125 °C	-	1.79	-	
Diode forward voltage	V <sub>F</sub>	V <sub>GE</sub> = 0V, I <sub>F</sub> = 15A				V
		T <sub>vj</sub> = 25 °C	-	1.10	1.30	
		T <sub>vj</sub> = 125 °C	-	1.05	-	
Gate-emitter threshold voltage	V <sub>GE(th)</sub>	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 1mA	4.3	-	6.3	V
		T <sub>vj</sub> = 175 °C	-	-	-	
Zero gate voltage collector current	I <sub>CES</sub>	V <sub>CE</sub> = 1350V, V <sub>GE</sub> = 0V				μA
		T <sub>vj</sub> = 25 °C	-	-	100.0	
Gate-emitter leakage current	I <sub>GES</sub>	V <sub>CE</sub> = 0V, V <sub>GE</sub> = 20V				nA
		T <sub>vj</sub> = 175 °C	-	-	100.0	
Transconductance	g <sub>fs</sub>	V <sub>CE</sub> = 20V, I <sub>CE</sub> = 15A	-	15.0	-	S

**Dynamic Characteristic**

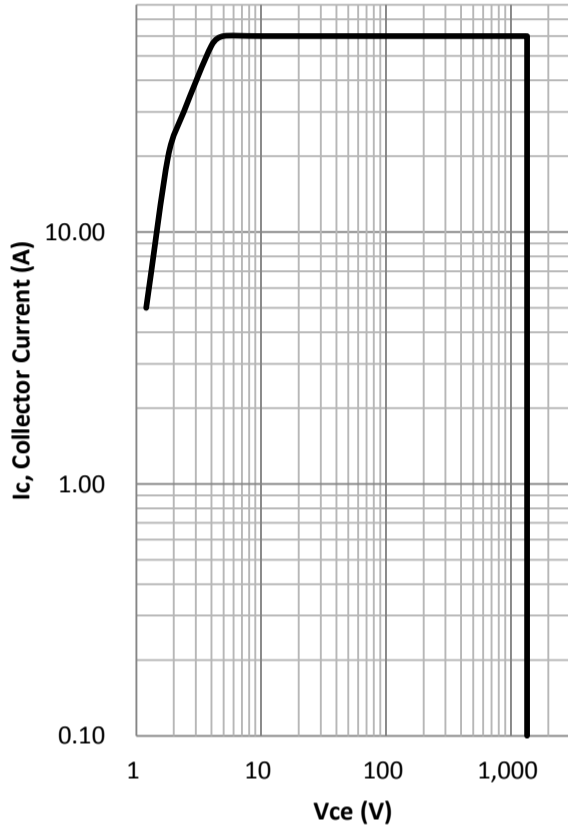
Input Capacitance	$C_{ies}$	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$	-	5000	-	pF
Output Capacitance	$C_{oes}$		-	380	-	
Reverse Transfer Capacitance	$C_{res}$		-	20	-	
Gate Total Charge	$Q_G$	$V_{CC} = 1080V, I_C = 15A, V_{GE} = 15V$	-	175	-	nC
Gate-Source charge	$Q_{gs}$		-	14	-	
Gate-Drain charge	$Q_{gd}$		-	110	-	
Turn-off delay time	$t_{d(off)}$	$T_{vj} = 25\text{ }^\circ\text{C}, V_{CC} = 600V, I_C = 15A, V_{GE} = 0.0/15.0V, R_G = 10.0\Omega$	-	220	-	ns
Fall time	$t_f$		-	140	-	
Turn-off energy	$E_{off}$		-	0.65	-	mj

**Electrical Characteristic (at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

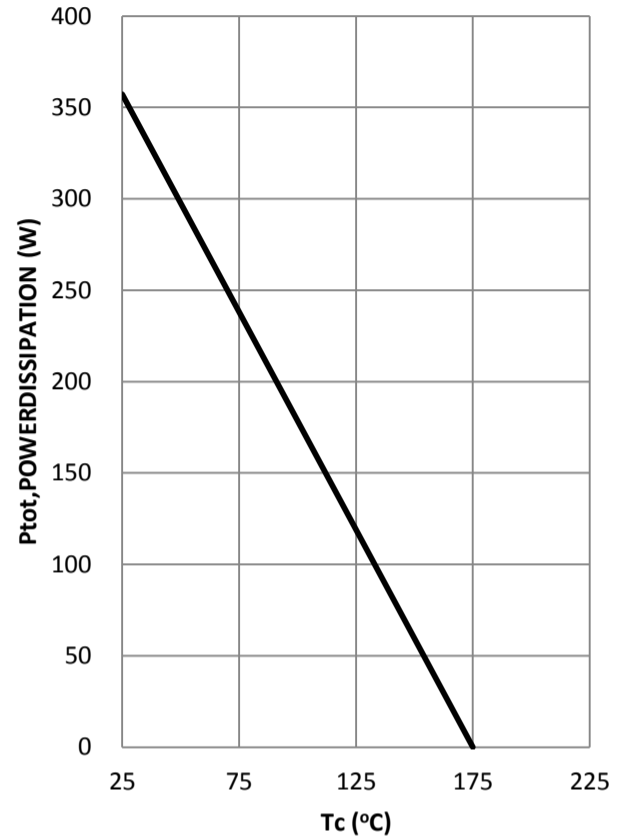
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Turn-off delay time	$t_{d(off)}$	$T_{vj} = 175\text{ }^\circ\text{C}$	-	210	-	ns
Fall time	$t_f$	$V_{CC} = 600V, I_C = 15A, V_{GE} = 0.0/15.0V, R_G = 10.0\Omega$	-	150	-	
Turn-off energy	$E_{off}$	$R_G = 10.0\Omega$	-	1.30	-	mj

## Typical Performance Characteristics

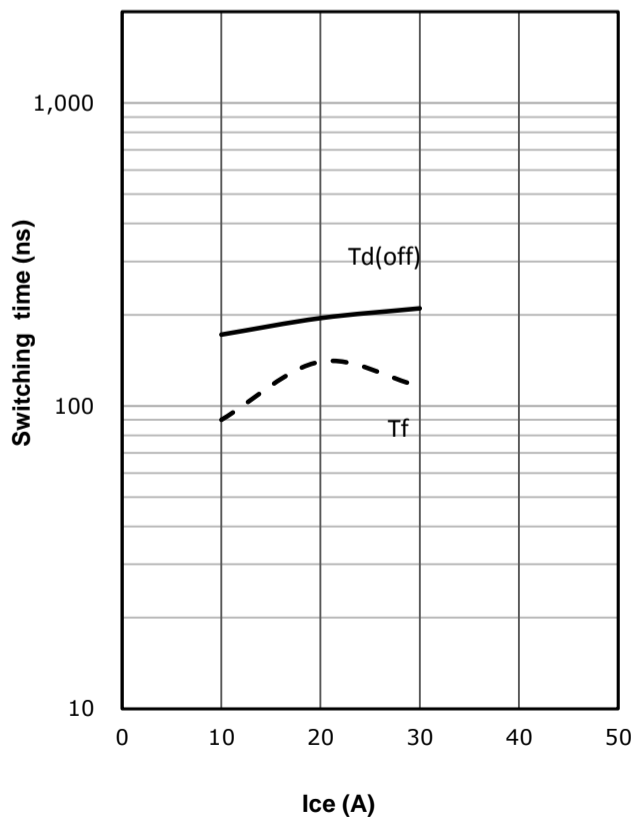
**Figure 1. Safe operating area**  
( $D=0, T_C=25^{\circ}\text{C}, T_{vj}=175^{\circ}\text{C}; V_{GE}=15\text{V}, t_p=1\mu\text{s}$ )



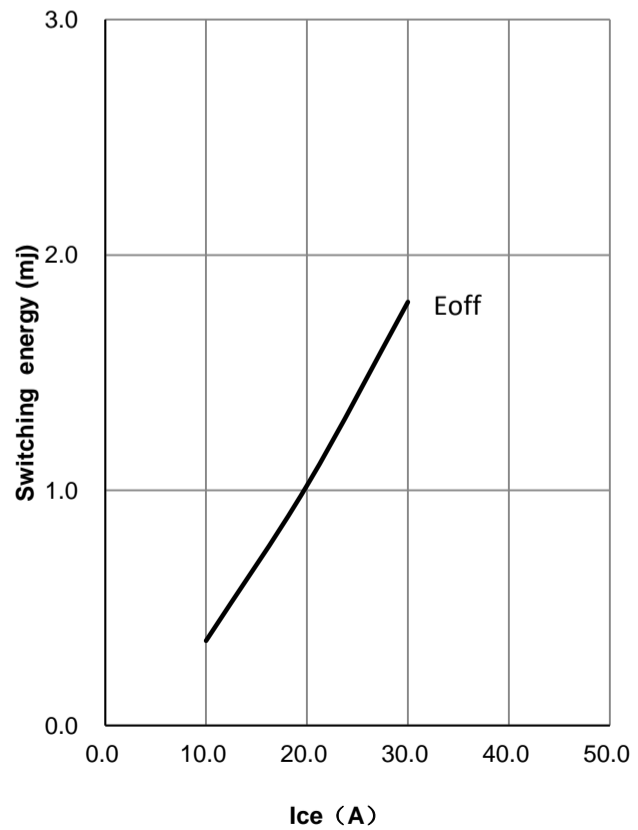
**Figure 2. Power dissipation as a function of case temperature ( $T_{vj}\leq 175^{\circ}\text{C}$ )**



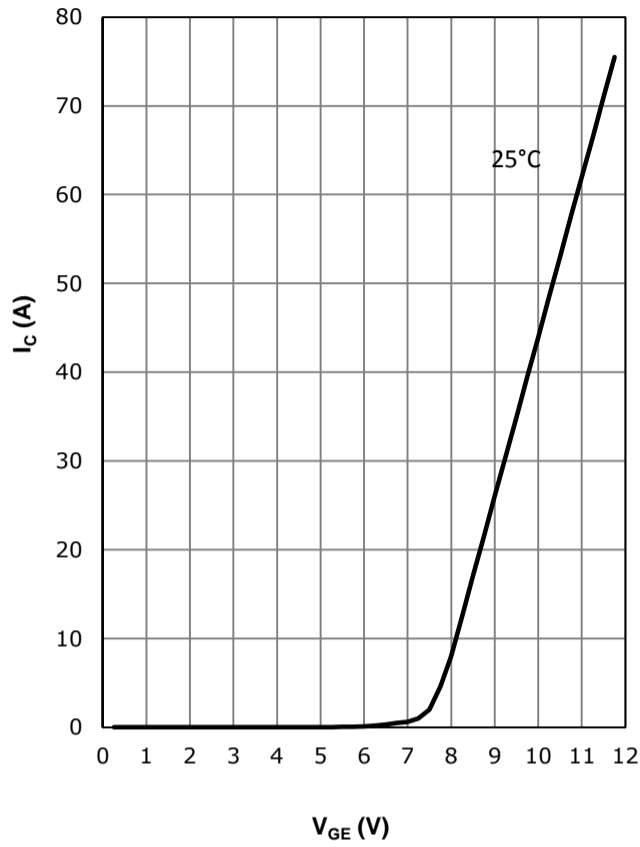
**Fig 3: Typical switching time Vs IC Characteristics ( $T_C=25^{\circ}\text{C}$ )**



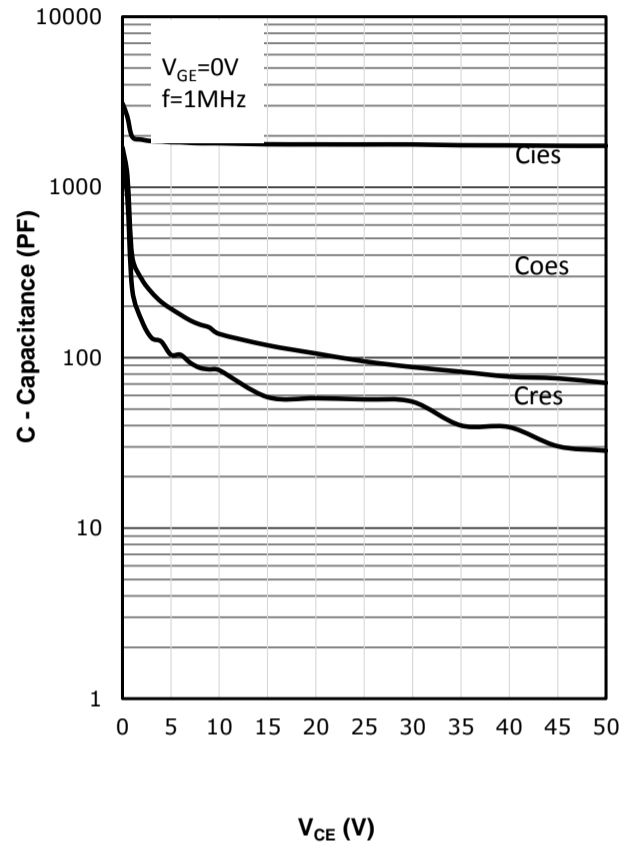
**Fig 4: Typical switching Energy Vs IC Characteristics ( $T_C=25^{\circ}\text{C}$ )**



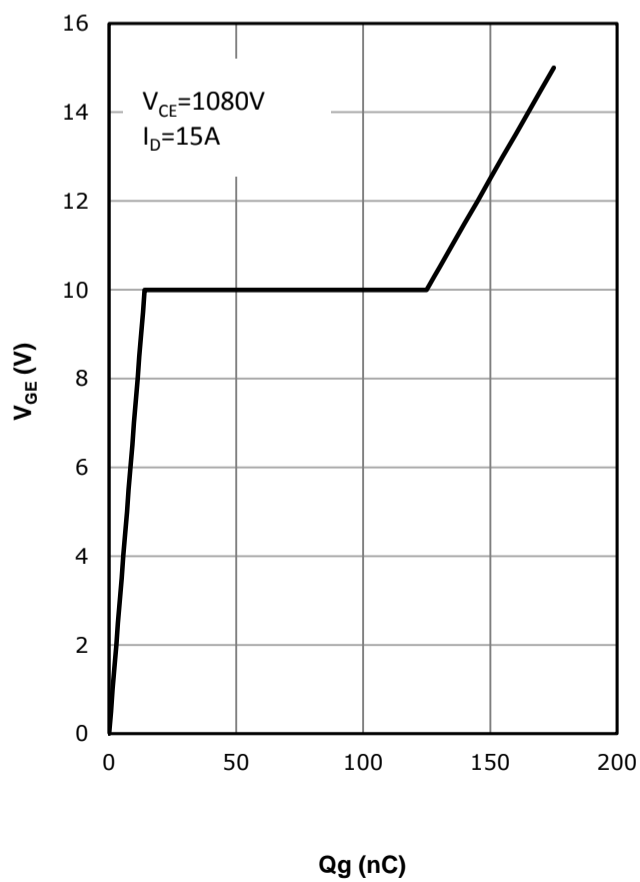
**Fig 5: Transfer Characteristics**



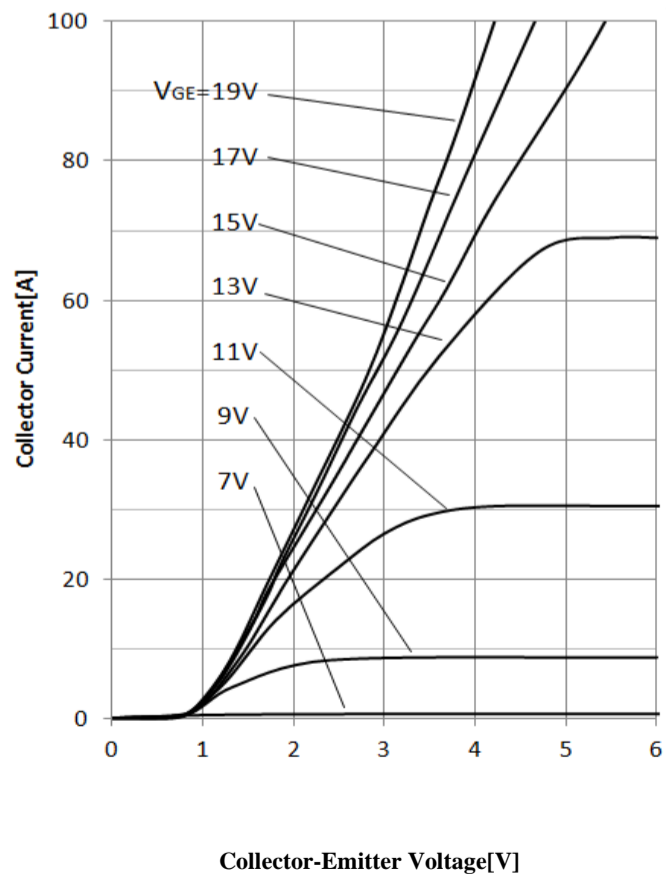
**Fig 6: Capacitance Characteristics**



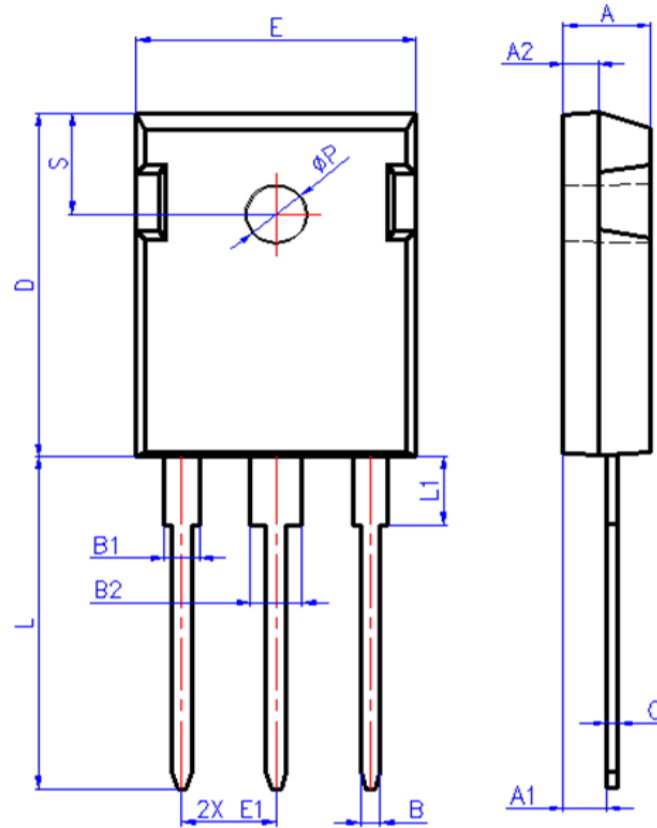
**Fig 7: Gate Charge Characteristics**



**Fig 8. Typical output characteristic ( $T_c = 25^\circ\text{C}$ )**



**Package Outline: TO-247-3L**



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.70	5.30
A1	2.30	2.70
A2	1.70	2.30
B	1.00	1.30
B1	1.80	2.20
B2	2.80	3.20
C	0.55	0.75
D	20.70	21.30
E	15.70	16.30
E1	5.15	5.75
L	19.80	20.80
L1	4.00	4.40
S	6.05	6.35
P	3.30	3.80

**Revision History**

Revision	Date	Major changes
1.0	2021/5/21	Release of formal version

**Disclaimer**

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